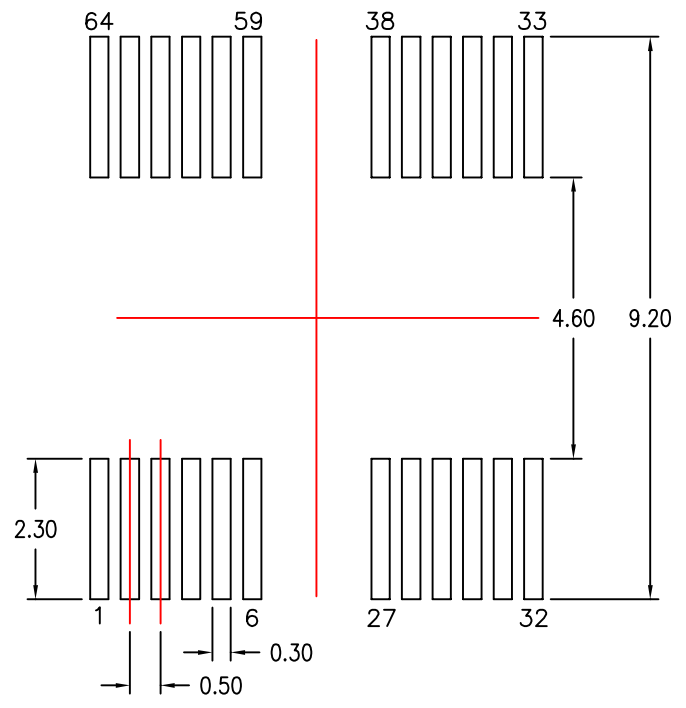
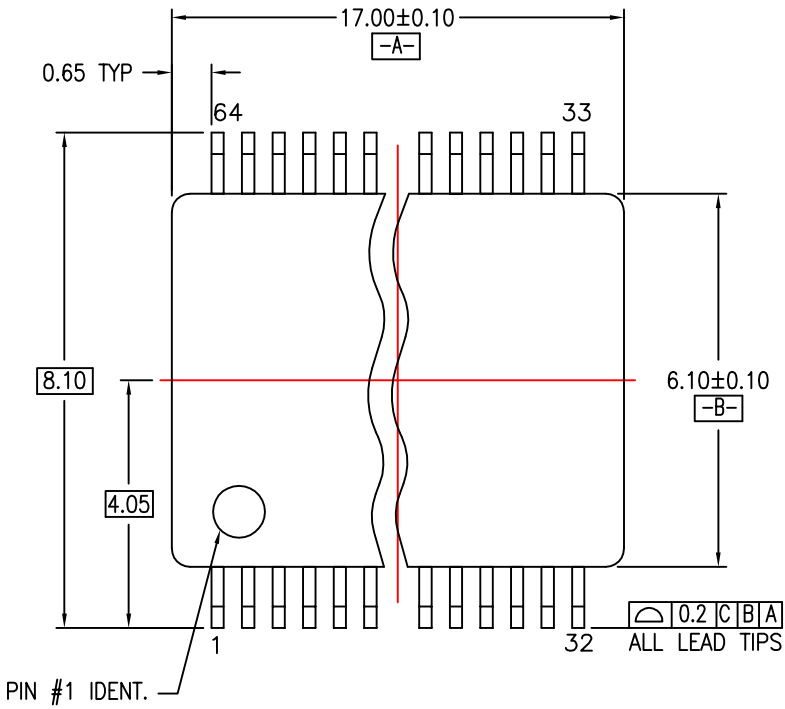
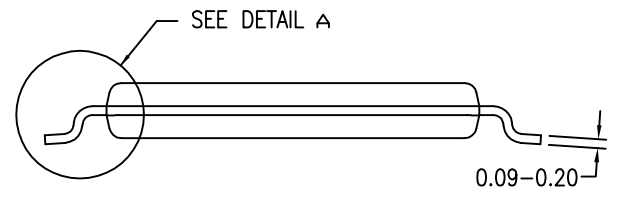
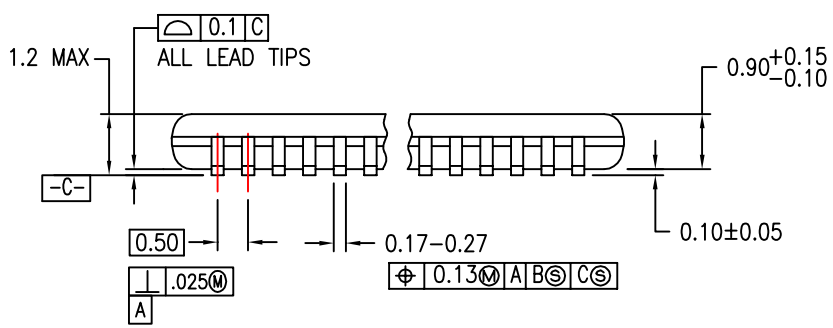


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REVISIONS				
LTR	DESCRIPTION	EDCN	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL		9-12-98	FEITAN
B	Corrected JEDEC Ref and added true position tol.		9-21-99	H.Allen



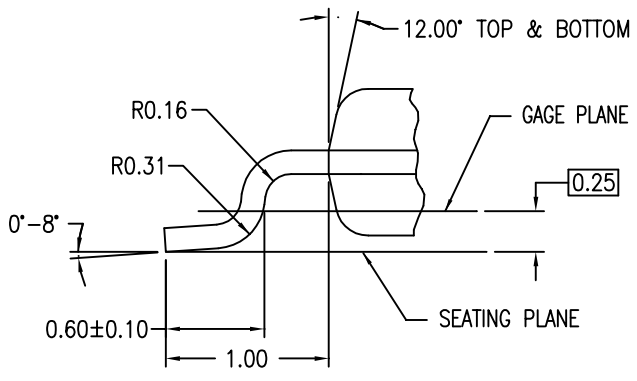
LAND PATTERN RECOMENDATION



DIMENSIONS ARE IN MILLIMETERS

NOTES:

- A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION EF, REF NOTE 6, DATE 7/93.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.



DETAIL A

MTD64REVB

APPROVALS		DATE	Bayan Lepas, FIZ, 11900, Penang, Malaysia.			
DRAWN		9-12-98				
DFTG. CHK.						
ENGR. CHK.						
			SCALE	SIZE	DRAWING NUMBER	REV
			N/A	C	MKT-MTD64	B
DO NOT SCALE DRAWING			SHEET 1 of 1			

64LD, TSSOP, JEDEC MO-153, 6.1MM WIDE